

**MICROELECTRONICS PACKAGE ASSEMBLY TOOL AND METHOD OF
MANUFACTURE THEREWITH**

ABSTRACT

[0024] A method of manufacturing a microelectronic package comprising, in one embodiment, providing a package substrate, coupling a device substrate to the package substrate, and assembling a bifurcated mold around the device and package substrates, the bifurcated mold including a seal. The method also includes encapsulating the device and package substrates employing the bifurcated mold.